

Chemicals contained in products

Package-type

Epson Package name; **QFP13-64PIN / Halogen free**

JEITA Package name; **P-LQFP064-1010-0.50**

Lead frame plating; **Lead(Pb) Free**

Weight; **0.35 [g] *Note1**

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	0.9	Silicon	7440-21-3	0.9	999894	Base material
			Boron	7440-42-8	0.000002	2	Dopant
			Phosphorus	7723-14-0	0.000005	5	Dopant
			Aluminum	7429-90-5	0.00002	20	Metalization
			Arsenic *Note3	7440-38-2	0.000005	5	Dopant
			Fluorine *Note3	7782-41-4	0.000002	2	Dopant
			Titanium *Note3	7440-32-6	0.00002	20	Metalization
			Molybdenum *Note3	7439-98-7	0.00002	20	Metalization
			Tungsten *Note3	7440-33-7	0.00003	30	Metalization
			Cobalt *Note3	7440-48-4	0.000002	2	Metalization
	Stress buffer coat	0.20	Polyimide	-	0.20	1000000	Stress buffer coat *Note4
Package	Die Bonding material	0.96	Silver	7440-22-4	0.87	910000	Base material
			Acrylic resin	-	0.07	70000	Adhesive
			Epoxy resin	-	0.02	20000	Adhesive
	Lead Frame Plating	1.85	Tin	7440-31-5	1.85	1000000	Solder
	Lead Frame	114.50	Copper	7440-50-8	108.20	945000	Conductor
			Silver	7440-22-4	0.57	5000	Inner lead plating
			Others *Note5	-	5.73	50000	Additive
	Bonding Wire	1.00	Gold	7440-57-5	1.00	1000000	Conductor
	Mold resin	230.55	Epoxy resin	-	14.52	63000	Base material
			Silica	60676-86-0/-	202.88	880000	Filler
			Carbon black	1333-86-4	0.46	2000	Coloring agent
			Hardening chemical(ex:Phenol resin)	-	9.22	40000	Base material
			Organic phosphorous compound	-	1.15	5000	Hardening accelerator
			others	-	2.31	10000	Additive

Regarding the information of chemical substances

*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

*Note4 The stress buffer coat may not be used depending on the individual model.

*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included.